

For an interconnect scaling, excellent planarity, and higher reliability

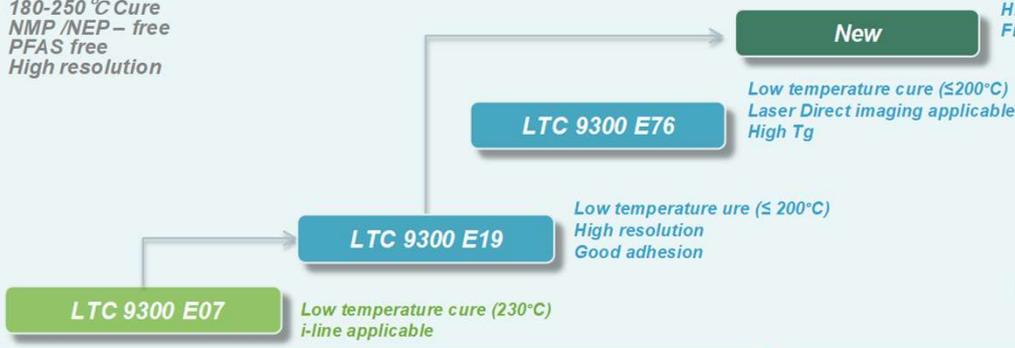
Photosensitive polyimide material **ZEMATES™**

Be a trusted partner "MATES" driving innovation for our customers, supporting the future of the semiconductor industry together

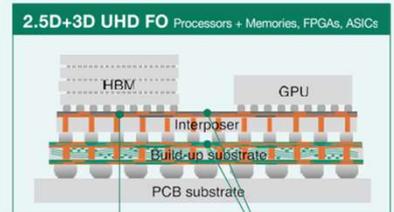
Product roadmap

Advanced RDL dielectric for WLP/PLP

180-250 °C Cure
NMP /NEP – free
PFAS free
High resolution



Low temperature cure (≤ 190°C)
High resolution
High modulus
Film type



Liquid type polyimide
Film type polyimide

Advanced Buffercoat layer

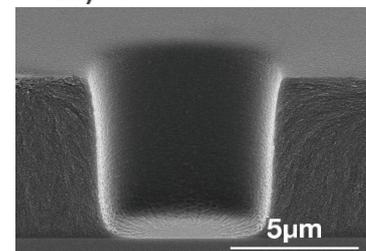
300-400 °C Cure
NMP/NEP



Liquid type polyimide

- A wide range of mechanical/thermal properties enable it to be applied to various RDL.
- Contributing to interconnect scaling with high resolution.
- Excellent reliability performance applicable to advanced packaging.

Ex) 5um Via/6.5um FT



Film type polyimide

- Multi-layered RDL is achievable with an excellent planarity by the vacuum laminating process.
- Applicable to a panel process enabling productivity improvements.
- Excellent reliability performance applicable to advanced packaging.

Ex) 7um Via/10um FT

